



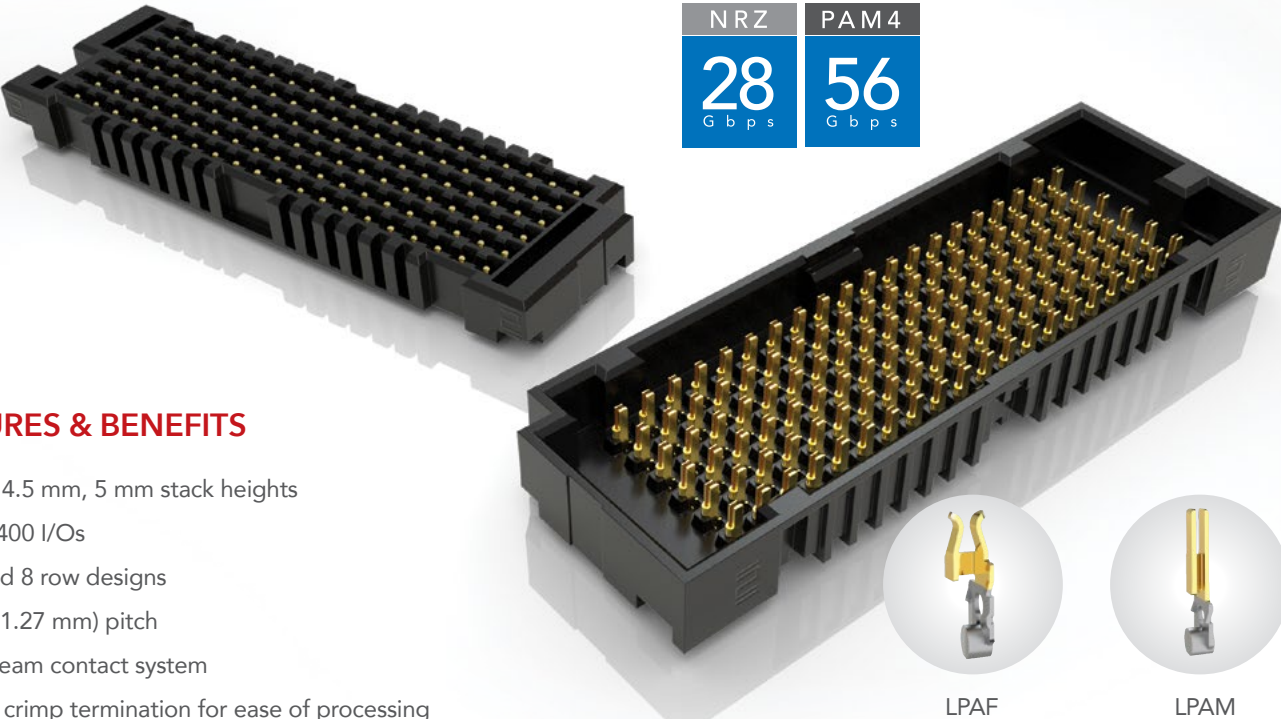
**THE DATASHEET OF
LPAM-10-01.0-L-04-2-K-TR**



LPARRAY™

LOW PROFILE OPEN-PIN-FIELD ARRAYS

(1.27 mm) .050" PITCH




NRZ
28
Gbps


PAM4
56
Gbps

FEATURES & BENEFITS

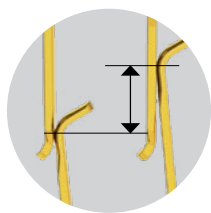
- 4 mm, 4.5 mm, 5 mm stack heights
- Up to 400 I/Os
- 4, 6 and 8 row designs
- .050" (1.27 mm) pitch
- Dual beam contact system
- Solder crimp termination for ease of processing
- Board stacking standoffs available to assist with unmating and reduce risk for component damage on board



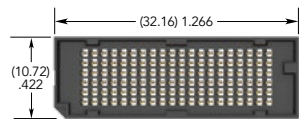
LPAF
Dual Beam Contact



LPAM
Dual Blade Terminal

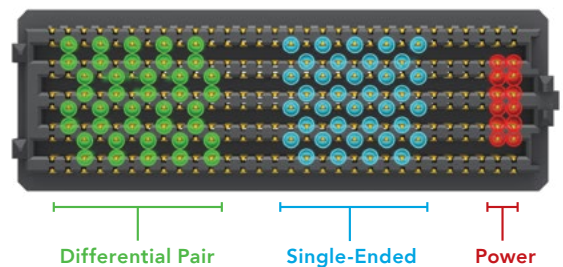


(0.51 mm) .020"
Nominal Wipe



LPAM Series; 120 pins

MAXIMUM GROUNDING & ROUTING FLEXIBILITY



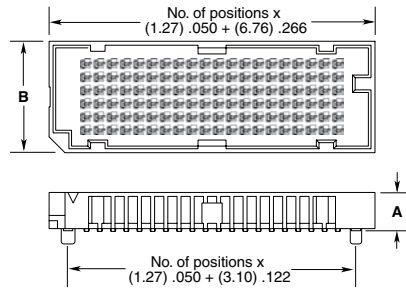
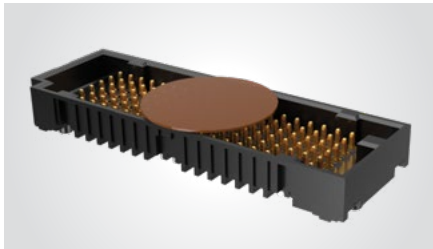
KEY SPECIFICATIONS (LPAM/LPAF)

PITCH	TOTAL PINS	INSULATOR MATERIAL	CONTACT MATERIAL	PLATING	CURRENT RATING	WORKING VOLTAGE	LEAD-FREE SOLDERABLE
1.27 mm x 1.27 mm	Up to 400 I/Os	Black LCP	Copper Alloy	Au or Sn over 50 μ" (1.27 μm) Ni	2.2 A per pin (8 adjacent pins powered)	250 VAC	YES

(1.27 mm) .050" PITCH • LOW PROFILE OPEN-PIN-FIELD ARRAYS

SERIES	NO. PINS PER ROW	LEAD STYLE	PLATING OPTION	NO. OF ROWS	SOLDER TYPE	K	"X"R
LPAM Terminal	-10, -20, -30, -40,	-01.0 = (1.0 mm) .039" (LPAM only)	-L = 10 μ" (0.25 μm) Gold on contact area, Matte Tin on solder tail	-04 -06 -08	-1 = Tin/Lead Alloy Solder Crimp		-K = Polyimide film Pick & Place Pad
LPAF Socket	-50 (-08 rows only)	-01.5 = (1.5 mm) .060" (LPAM only)	-S = 30 μ" (0.76 μm) Gold on contact area, Matt Tin on solder tail		-2 = Lead-Free Solder Crimp		-TR =Tape & Reel
		-03.0 = (3.0 mm) .118" (LPAF only)					-FR =Full Reel Tape & Reel (must order max. quantity per reel; contact Samtec for quantity breaks)
		-03.5 = (3.5 mm) .138" (LPAF only)					

LPAM
Board Mates:
LPAF
Standoffs:
JSO, SO

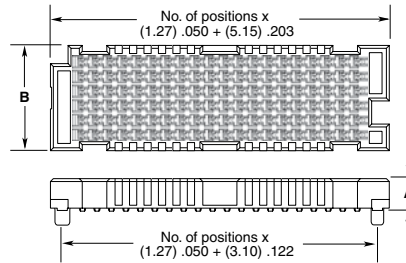
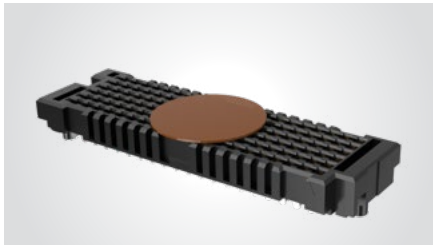


NO. OF ROWS	B
-04	(8.18) .322
-06	(10.72) .422
-08	(13.26) .522

LEAD STYLE	A
-01.0	(3.68) .145
-01.5	(4.19) .165

View complete specifications at: samtec.com?LPAM

LPAF
Board Mates:
LPAM
Standoffs:
JSO, SO



NO. OF ROWS	B
-04	(6.71) .264
-06	(9.25) .364
-08	(11.79) .464

LEAD STYLE	A
-03.0	(2.79) .110
-03.5	(3.30) .130

MATED HEIGHTS*		
LPAM LEAD STYLE	LPAF LEAD STYLE	
	-03.0	-03.5
-01.0	(4.00) .157	(4.50) .177
-01.5	(4.50) .177	(5.00) .197

*Processing conditions will affect mated height.

Notes:
Some sizes, styles and options are non-standard, non-returnable

View complete specifications at: samtec.com?LPAF

Looking for pricing, stock, or lifecycle information?

Click below to explore more details on WIN SOURCE:

- ⊖ [View LPAM-10-01.0-L-04-2-K-TR on WIN SOURCE](#)
- ⊖ [Samtec Inc. Information](#)

Optimize Your Supply Chain with WIN SOURCE Solutions

- ✓ Global Sourcing Solution
- ✓ Obsolete Management
- ✓ Cost Control Management
- ✓ Shortage Management
- ✓ Alternative Solution
- ✓ Excess Inventory Management